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- (71) **Applicant (for all designated States except US):** **INTEL CORPORATION** [US/US]; 2200 Mission College Boulevard, Santa Clara, CA 95052 (US).
- (72) **Inventors; and**
- (75) **Inventors/Applicants (for US only):** **MANUSHAROW, Mathew J.** [US/US]; 16667 South 37th Place, Phoenix, AZ 85048 (US). **HLAD, Mark S.** [US/US]; 3131 S. Kimberlee Way, Chandler, AZ 85286 (US). **NALLA, Ravi K.** [IN/US]; 3472 Williams Road, San Jose, CA 95117 (US).
- (74) **Agents:** **VINCENT, Lester J.** et al.; Blakely Sokoloff Taylor & Zafman, 1279 Oakmead Parkway, Sunnyvale, CA 94085 (US).

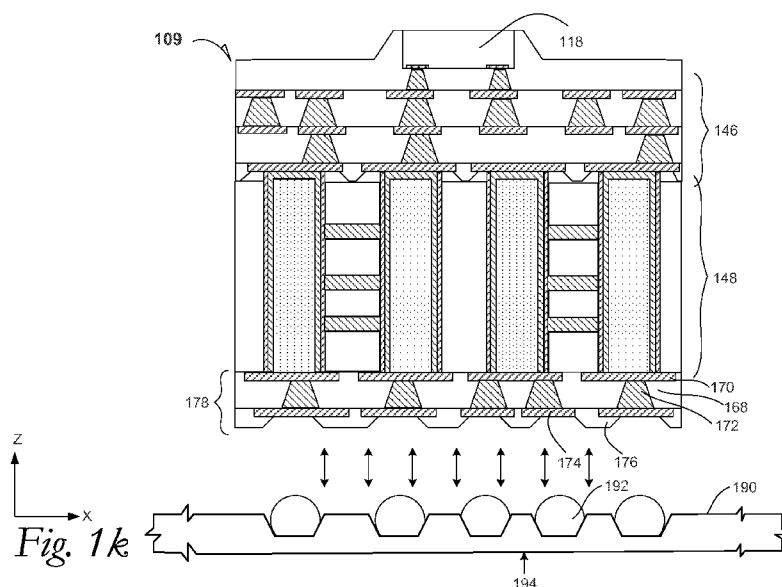
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(54) **Title:** BUMPLESS BUILD-UP LAYER AND LAMINATED CORE HYBRID STRUCTURES AND METHODS OF ASSEMBLING SAME



(57) **Abstract:** A structure includes a hybrid substrate for supporting a semiconductive device that includes a bumpless build-up layer in which the semiconductive device is embedded and a laminated-core structure. The bumpless build-up layer and the laminated-core structure are rendered an integral apparatus by a reinforcement plating that connects to a plated through hole in the laminated-core structure and to a subsequent bond pad of the bumpless build-up layer structure.

